Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

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Address: A1208, Overseas Decoration Building, #122 Zhenhua RD., Futian, Shenzhen, China

NL27WZU04

Dual Unbuffered Inverter

The NL27WZU04 is a high performance dual unbuffered inverter operating from a 1.65 to 5.5 V supply. These devices are well suited for use as oscillators, pulse shapers, and in many other applications requiring a high−input impedance amplifier. For digital applications, the NL27WZ04 is recommended.

Features

- Designed for 1.65 V to 5.5 V V_{CC} Operation
- Unbuffered for Crystal Oscillator and Analog Applications
- LVCMOS Compatible
- Source/Sink ±16 mA @ 4.5 V V_{CC}
- Near Zero Static Supply Current Substantially Reduces System Power Requirements
- Chip Complexity: FET = 72; Equivalent Gate = 18
- These Devices are Pb−Free and are RoHS Compliant
- NLV Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC−Q100 Qualified and PPAP Capable

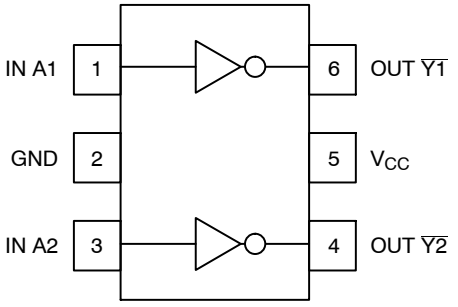


Figure 1. Pinout (Top View)

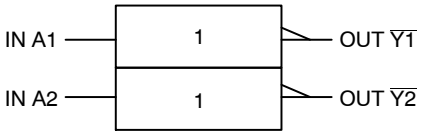


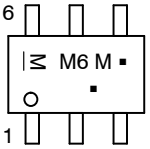
Figure 2. Logic Symbol

ON Semiconductor®

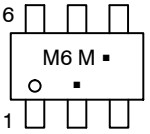
http://onsemi.com

MARKING DIAGRAMS

SC−88/SOT−363/SC−70
DF SUFFIX
CASE 419B



TSOP−6
DT SUFFIX
CASE 318G



M6 = Device Code
M = Date Code*
▪ = Pb−Free Package

(Note: Microdot may be in either location)

*Date Code orientation and/or position may vary depending upon manufacturing location.

PIN ASSIGNMENT

Pin	Function
1	IN A1
2	GND
3	IN A2
4	OUT $\overline{Y2}$
5	V_{CC}
6	OUT $\overline{Y1}$

FUNCTION TABLE

A Input	$\overline{Y}$ Output
L	H
H	L

ORDERING INFORMATION

See detailed ordering and shipping information in the package dimensions section on page 4 of this data sheet.

MAXIMUM RATINGS

Symbol	Characteristics	Value	Units
V_{CC}	DC Supply Voltage	−0.5 to +7.0	V
V_I	DC Input Voltage	$-0.5 \le V_I \le V_{CC}$	V
V_O	DC Output Voltage	−0.5 to +7.0	V
I_{IK}	DC Input Diode Current V_I < GND	 −50	mA
I_{OK}	DC Output Diode Current V_O < GND V_O > V_{CC}	 −50 +50	mA
I_O	DC Output Sink Current	±50	mA
I_{CC}	DC Supply Current per Supply Pin	±100	mA
I_{GND}	DC Ground Current per Ground Pin	±100	mA
T_{STG}	Storage Temperature Range	−65 to +150	°C
P_D	Power Dissipation in Still Air SC−88, TSOP−6	 200	mW
θ_{JA}	Thermal Resistance SC−88, TSOP−6	 333	°C/W
T_L	Lead Temperature, 1 mm from Case for 10 s	260	°C
T_J	Junction Temperature under Bias	+150	°C
V_{ESD}	ESD Withstand Voltage Human Body Model (Note 1) Machine Model (Note 2) Charged Device Model (Note 3)	 > 2000 > 200 N/A	V
$I_{Latchup}$	Latchup Performance Above V_{CC} and Below GND at 85°C (Note 4)	 ±500	mA

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

1. Tested to EIA/JESD22−A114−A.
2. Tested to EIA/JESD22−A115−A.
3. Tested to JESD22−C101−A.
4. Tested to EIA/JESD78.

RECOMMENDED OPERATING CONDITIONS

Symbol	Parameter	Min	Max	Units
V_{CC}	Supply Voltage Operating Data Retention Only	 1.65 1.5	 5.5 5.5	V
V_I	Input Voltage	0	5.5	V
V_O	Output Voltage (High or LOW State)	0	5.5	V
T_A	Operating Free−Air Temperature	−55	+125	°C
$\Delta t/\Delta V$	Input Transition Rise or Fall Rate V_{CC} = 2.5 V ± 0.2 V V_{CC} = 3.0 V ± 0.3 V V_{CC} = 5.0 V ± 0.5 V	 0 0 0	 20 10 5	ns/V

DC ELECTRICAL CHARACTERISTICS

Symbol	Parameter	Condition	V_{CC} (V)	T_A = 25°C			−55°C ≤ T_A ≤ 125°C		Units
				Min	Typ	Max	Min	Max	
V_{IH}	High−Level Input Voltage		1.65 to 1.85	0.85 V_{CC}			0.85 V_{CC}		V
			2.3 to 5.5	0.8 V_{CC}			0.8 V_{CC}		
V_{IL}	Low−Level Input Voltage		1.65 to 1.85			0.15 V_{CC}		0.15 V_{CC}	V
			2.3 to 5.5			0.2 V_{CC}		0.2 V_{CC}	
V_{OH}	High−Level Output Voltage V_{IN} = V_{IL}	I_{OH} = −100 μA	1.65 to 5.5	V_{CC}−0.1			V_{CC}−0.1		V
	V_{IN} = GND	I_{OH} = −3 mA	1.65	1.29	1.52		1.29		
		I_{OH} = −4 mA	2.3	1.9	2.1		1.9		
		I_{OH} = −6 mA	2.7	2.2	2.3		2.2		
		I_{OH} = −8 mA	3.0	2.4	2.6		2.4		
		I_{OH} = −12 mA	3.0	2.3	2.5		2.3		
		I_{OH} = −16 mA	4.5	3.8	4.2		3.8		
V_{OL}	Low−Level Output Voltage V_{IN} = V_{IH}	I_{OL} = 100 μA	1.65 to 5.5			0.1		0.1	V
	V_{IN} = V_{CC}	IOL = 3 mA	1.65		0.08	0.24		0.24	
		I_{OL} = 4 mA	2.3		0.12	0.3		0.3	
		I_{OL} = 6 mA	2.7		0.20	0.4		0.4	
		I_{OL} = 8 mA	3.0		0.24	0.4		0.4	
		I_{OL} = 12 mA	3.0		0.26	0.55		0.55	
		I_{OL} = 16 mA	4.5		0.31	0.55		0.55	
I_{IN}	Input Leakage Current	V_{IN} = 5.5 V or GND	0 to 5.5			±0.1		±1.0	μA
I_{OFF}	Power Off Leakage Current	V_{IN} = 5.5 V or V_{OUT} = 5.5 V	0			1		10	μA
I_{CC}	Maximum Quiescent Supply Current	V_{IN} = 5.5 V or GND	5.5			1.0		10	μA

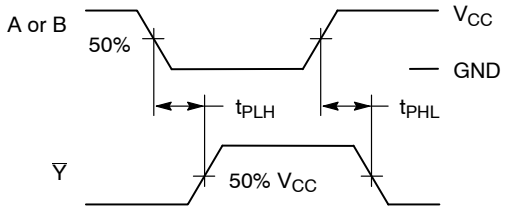
AC ELECTRICAL CHARACTERISTICS t_R = t_F = 2.5 ns; C_L = 50 pF; R_L = 500 Ω

Symbol	Parameter	Condition	V_{CC} (V)	T_A = 25°C			−55°C ≤ T_A ≤ 125°C		Units
				Min	Typ	Max	Min	Max	
t_{PLH} t_{PHL}	Propagation Delay Input A to Y (Figure 3 and 4)	R_L = 1 MΩ, C_L = 50 pF	1.8 ± 0.15	1.5	5.5	1.8	1.5	11.0	ns
		R_L = 1 MΩ, C_L = 15 pF	2.5 ± 0.2	1.2	3.3	5.7	1.2	6.3	
		R_L = 1 MΩ, C_L = 15 pF	3.3 ± 0.3	0.8	2.7	4.1	0.8	4.5	
		R_L = 500 Ω, C_L = 50 pF		1.2	4.0	6.4	1.2	7.0	
		R_L = 1 MΩ, C_L = 15 pF	5.0 ± 0.5	0.5	2.2	3.3	0.5	3.6	
		R_L = 500 Ω, C_L = 50 pF		0.8	3.4	5.6	0.8	6.2	

CAPACITIVE CHARACTERISTICS

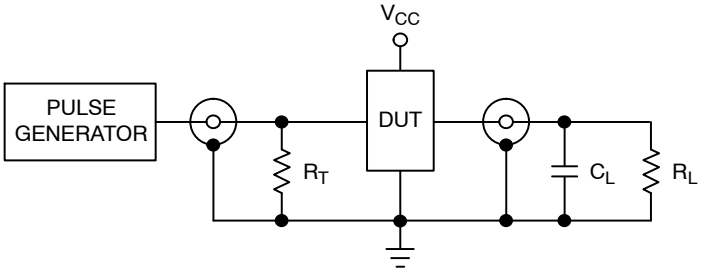
Symbol	Parameter	Condition	Typical	Units
C_{IN}	Input Capacitance	V_{CC} = 5.5 V, V_I = 0 V or V_{CC}	7	pF
C_{OUT}	Output Capacitance	V_{CC} = 5.5 V, V_I = 0 V or V_{CC}	8	pF
C_{PD}	Power Dissipation Capacitance (Note 5)	10 MHz, V_{CC} = 5.5 V, V_I = 0 V or V_{CC}	25	pF

5. C_{PD} is defined as the value of the internal equivalent capacitance which is calculated from the operating current consumption without load. Average operating current can be obtained by the equation: $I_{CC(OPR)}$ = C_{PD} • V_{CC} • f_{in} + I_{CC}. C_{PD} is used to determine the no−load dynamic power consumption; P_D = C_{PD} • V_{CC}^2 • f_{in} + I_{CC} • V_{CC}.



PROPAGATION DELAYS
$t_R = t_F$ = 2.5 ns, 10% to 90%; f = 1 MHz; t_W = 500 ns

Figure 3. Switching Waveforms



C_L = 50 pF or equivalent (includes jig and probe capacitance)
$R_L = R_1$ = 500 Ω or equivalent
$R_T = Z_{OUT}$ of pulse generator (typically 50 Ω)

Figure 4. Test Circuit

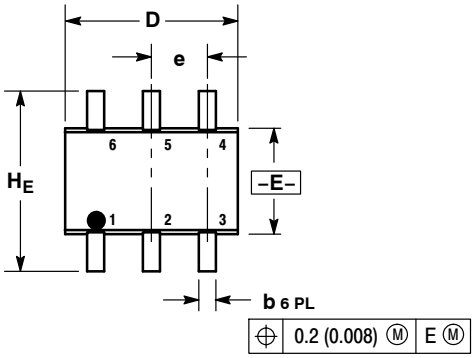
ORDERING INFORMATION

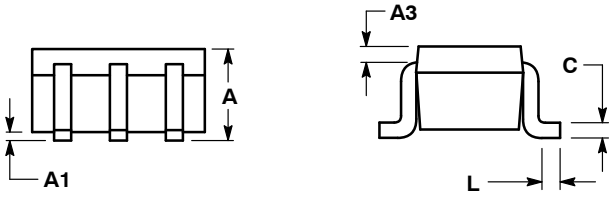
Device	Package	Shipping†
NL27WZU04DFT2G	SC−88 / SOT−363 / SC−70 (Pb−Free)	3000 / Tape & Reel
NLV27WZU04DFT2G*	SC−88 / SOT−363 / SC−70 (Pb−Free)	3000 / Tape & Reel
NL27WZU04DTT1G	TSOP−6 (Pb−Free)	3000 / Tape & Reel

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.
*NLV Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC−Q100 Qualified and PPAP Capable.

PACKAGE DIMENSIONS

SC−88/SC70−6/SOT−363
CASE 419B−02
ISSUE W

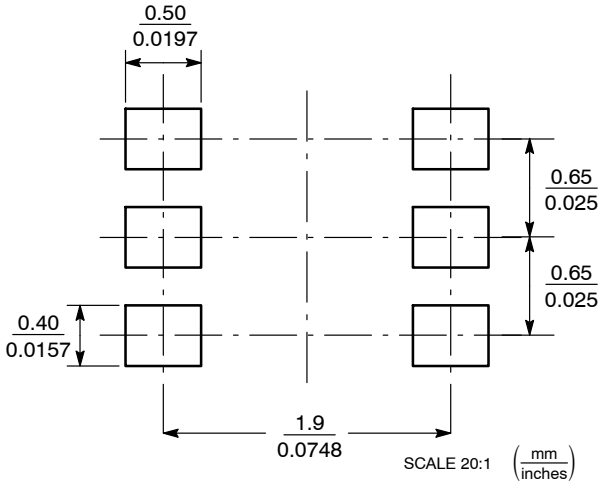




NOTES:
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: INCH.
3. 419B−01 OBSOLETE, NEW STANDARD 419B−02.

	MILLIMETERS			INCHES		
DIM	MIN	NOM	MAX	MIN	NOM	MAX
A	0.80	0.95	1.10	0.031	0.037	0.043
A1	0.00	0.05	0.10	0.000	0.002	0.004
A3		0.20 REF			0.008 REF	
b	0.10	0.21	0.30	0.004	0.008	0.012
C	0.10	0.14	0.25	0.004	0.005	0.010
D	1.80	2.00	2.20	0.070	0.078	0.086
E	1.15	1.25	1.35	0.045	0.049	0.053
e		0.65 BSC			0.026 BSC	
L	0.10	0.20	0.30	0.004	0.008	0.012
H_E	2.00	2.10	2.20	0.078	0.082	0.086

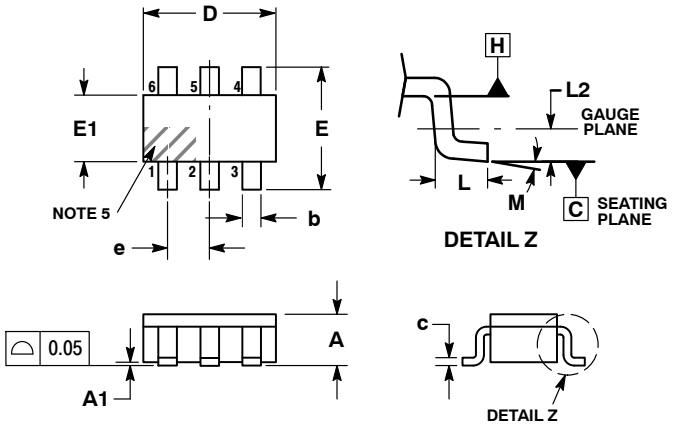
SOLDERING FOOTPRINT*



*For additional information on our Pb−Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

PACKAGE DIMENSIONS

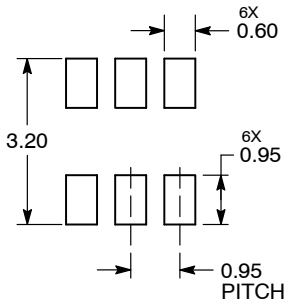
TSOP−6
CASE 318G−02
ISSUE U



NOTES:
1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS.
3. MAXIMUM LEAD THICKNESS INCLUDES LEAD FINISH. MINIMUM LEAD THICKNESS IS THE MINIMUM THICKNESS OF BASE MATERIAL.
4. DIMENSIONS D AND E1 DO NOT INCLUDE MOLD FLASH, PROTRUSIONS, OR GATE BURRS. MOLD FLASH, PROTRUSIONS, OR GATE BURRS SHALL NOT EXCEED 0.15 PER SIDE. DIMENSIONS D AND E1 ARE DETERMINED AT DATUM H.
5. PIN ONE INDICATOR MUST BE LOCATED IN THE INDICATED ZONE.

	MILLIMETERS		
DIM	MIN	NOM	MAX
A	0.90	1.00	1.10
A1	0.01	0.06	0.10
b	0.25	0.38	0.50
c	0.10	0.18	0.26
D	2.90	3.00	3.10
E	2.50	2.75	3.00
E1	1.30	1.50	1.70
e	0.85	0.95	1.05
L	0.20	0.40	0.60
L2	0.25 BSC		
M	0°	–	10°

RECOMMENDED SOLDERING FOOTPRINT*



DIMENSIONS: MILLIMETERS

*For additional information on our Pb−Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

PUBLICATION ORDERING INFORMATION

LITERATURE FULFILLMENT:
Literature Distribution Center for ON Semiconductor
P.O. Box 5163, Denver, Colorado 80217 USA
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Fax: 303−675−2176 or 800−344−3867 Toll Free USA/Canada
Email: orderlit@onsemi.com

N. American Technical Support: 800−282−9855 Toll Free USA/Canada
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